

PCN# 20150603000
Qualification of GTBF as Additional Assembly/Test Site
for Select Devices
Change Notification / Sample Request

Date: 6/8/2015
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150603000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM317KCS	null
UA78M33CKCS	null
UA78M05CKCS	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150603000	PCN Date:	06/08/2015
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Title: Qualification of GTBF as Additional Assembly/Test Site for Select Devices

Customer Contact: [PCN Manager](#) **Dept:** Quality Services

Proposed 1st Ship Date: 09/08/2015 **Estimated Sample Availability:** Date Provided at Sample request

<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Qualification of GTBF as additional assembly and test site for Select Devices. Assembly differences are shown in the following table:

Group 1 Device:

	NFME	GTBF
Mount Compound	SID# MC-05	SID# EY0000006
Mold Compound	SID# R-12	SID# EN0000038

Group 2 Device:

	NFME	GTBF
Mount Compound	SID# MC-05	SID# EY0000006
Mold Compound	SID# R-12	SID# EN0000038
Wire type	Au	Cu

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
NFME	Assembly Site Origin (22L)	ASO: NFM
GTBF (Great Team Backend Foundry)	Assembly Site Origin (22L)	ASO: GTF

Sample product shipping label (not actual product label)

ASSEMBLY SITE CODES: NFME = E, GTBF = TBD

Group 1 Product Affected:			
TLV1117CKCS	UA78M05CKCS	UA78M08CKCS	UA78M33CKCS
TLV1117CKCSE3	UA78M05CKCSE3	UA78M08CKCSE3	UA78M33CKCSE3
TLV1117IKCS	UA78M05IKCS	UA78M12CKCS	
TLV1117IKCSE3	UA78M05IKCSE3	UA78M12CKCSE3	
Group 2 Product Affected:			
LM317KCS	LM317KCSE3		

Qualification Report

Qualify GTBF as subcon A/T site for 3pin TO-220 KCS PWR Packages

Product Attributes

Attributes	Qual Device: LM317KCS
Assembly Site	GTBF
Package Family	TO-220
Flammability Rating	UL-V94-0
Wafer Fab Supplier	SFAB
Wafer Fab Process	J11

- QBS: Qual By Similarity
- Qual Device LM317KCS is qualified at Not Classified

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM317KCS
AC	Autoclave 121C	96 Hours	3/237/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/255/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
LI	Lead Fatigue	Leads	3/24/0
LI	Lead Pull to Destruction	Leads	3/24/0
MISC	Salt Atmosphere	Salt/Atmos	3/66/0
MQ	Manufacturability	(per mfg. Site specification)	3/Pass
PD	Physical Dimensions	(per mechanical drawing)	3/15/0
PKG	Lead Finish Adhesion	Leads	3/24/0
PKG	Solder Heat	10 sec	3/66/0
SD	Solderability	8 Hours Steam Age	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/273/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com